provide an electronic device or an electronic appliance containing the composition.

Solution to Problem

[0009]

One aspect relates to an underfill sealant composition comprising: (a) ~~20-60~~45% of a (meth)acrylic compound; (b) ~~1-20~~10% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide; (c) ~~0.001-20~~5% of an isocyanuric acid having an allyl group; (d) 0.1-5% of a radical initiator; and (e) ~~10-80~~50% of a filler, wherein all % are based on the total weight of the composition.

Another aspect relates to an electronic device comprising a cured product of the composition as disclosed herein.

Yet another aspect relates to an electronic appliance comprising the electronic device as defined above.

The present disclosure further relates to the following items.

[0010]

1. An underfill sealant composition comprising:

(a) a (meth)acrylic compound and

(c) an isocyanuric acid having an allyl group.

[0011]

2. The composition according to the above item 1, further comprising (b) a maleimide compound.

[0012]

3. The composition according to the above item 2, wherein the maleimide compound (b) comprises a bismaleimide.

[0013]

4. The composition according to any one of the above items 1 to 3, further comprising a radical initiator.

[0014]

CLAIMS

1. An underfill sealant composition comprising:
   (a) ~~20-60~~45% of a (meth)acrylic compound;
   (b) ~~1-20~~10% of a maleimide compound wherein the maleimide compound (b) comprises a bismaleimide;
   (c) ~~0.001-20~~5% of an isocyanuric acid having an allyl group;
   (d) 0.1-5% of a radical initiator; and
   (e) ~~10-80~~50% of a filler,
   wherein all % are based on the total weight of the composition.

2. The composition according to Claim 1, which is used in flip chip mounting.

3. An electronic device comprising a cured product of the composition according to any one of Claims 1 to 2.

4. An electronic appliance comprising the electronic device according to Claim 3.